

# APPROVAL SPECIFICATIONS

Title. NANO SIM+NANO SIM+TF三選二卡座

Product Model. MCS-303

Customer's Part NO.

Customer's Model:

## **Customer's Approval Requested.**

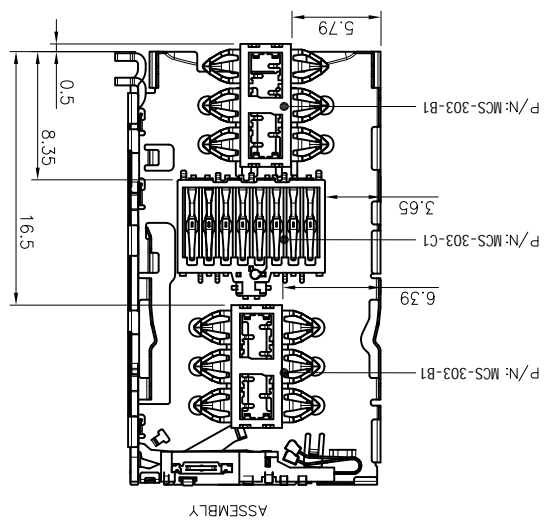
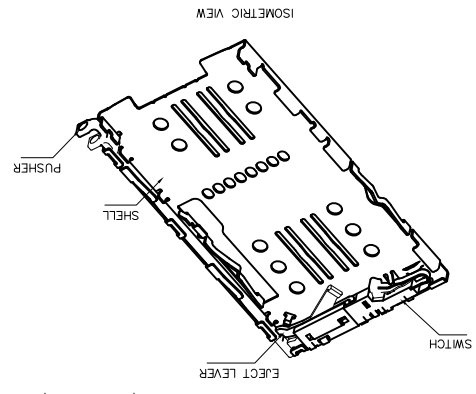
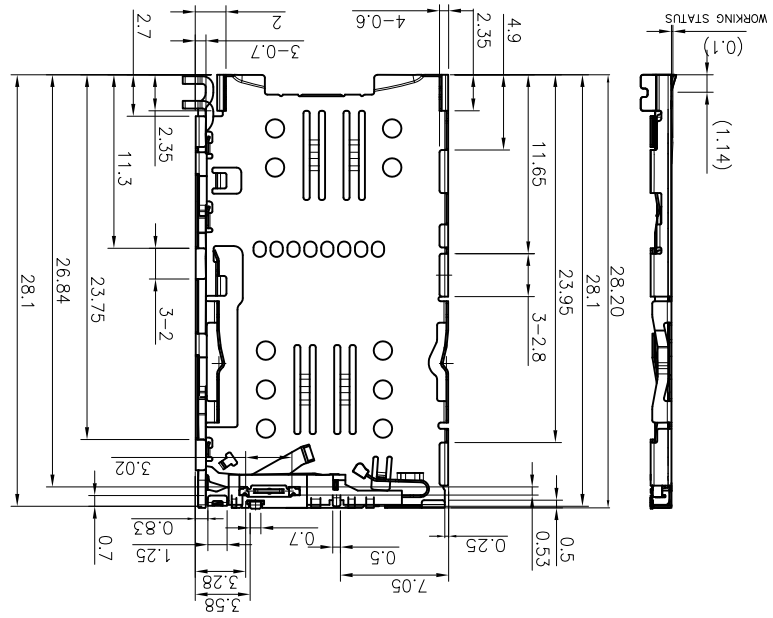
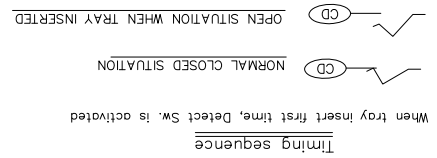
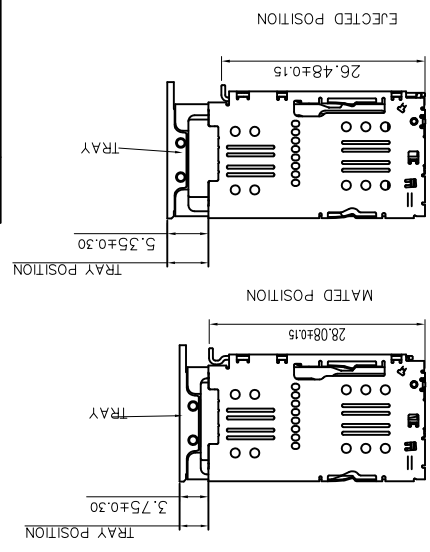
Please return this copy as a certification of your approval.

Checked by: \_\_\_\_\_ Date: \_\_\_\_\_

Approved by: \_\_\_\_\_ Date: \_\_\_\_\_

APPROVE	REVIEW	POLT
王凯	林永坚	陈旺

**XUNPU ELECTRONICS CO.,LTD**



Item	Description	Q'TY	Material	Finished
1	Switch Block	1	LCP	Under plate: 1.25 um Min Ni Solder area: Gold plating Contact area: Gold plating
2	Shell	1	SUS	Under plate: 1.25 um Min Ni Solder area: Gold plating Contact area: Gold plating
3	Pusher	1	SUS	N/A
4	Eject lever	1	SUS	N/A

UNLESS OTHERWISE SPECIFIED TOLERANCES			
DECIMALS:	ANGLES:	TITLE	1.35H Nano&f 3in2 with tray (Pin Push)Conn.Assem.
X : ±0.5	X X : ±2	DWN	ALLEN
X X : ±0.20	X X X : ±1	CHKD	KEVIN
X.XX : ±0.10		APVD	ERIC.W

CUSTOMER COPY			
REV: A	SHEET: 1 OF 1	SIZE: A3	SCALE: 1:1
UNIT: mm			
		PART NO.	MCS-303-A1

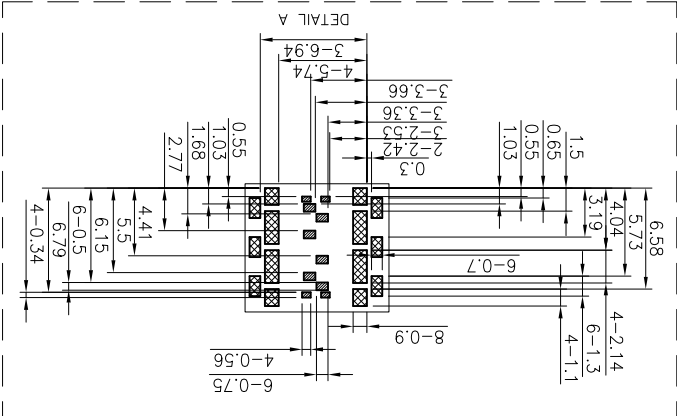
東莞市訊普電子科技有限公司

action and only for mechanical function

action and only for mechanical function

SMT process

UNLESS OTHERWISE SPECIFIED TOLERANCES		東莞市凱普電子科技有限公司	
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X XX : ±0.10		APVD	ERIC.W
		SIZE:	A3
		SHEET:	10F 1
		REV:	A
CUSTOMER COPY			



Pin	NAME
P13	Detect Switch
P1~P12	Ground

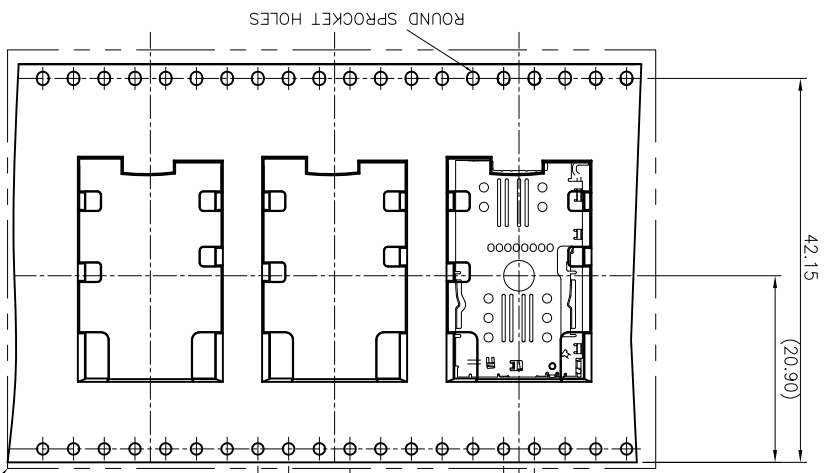
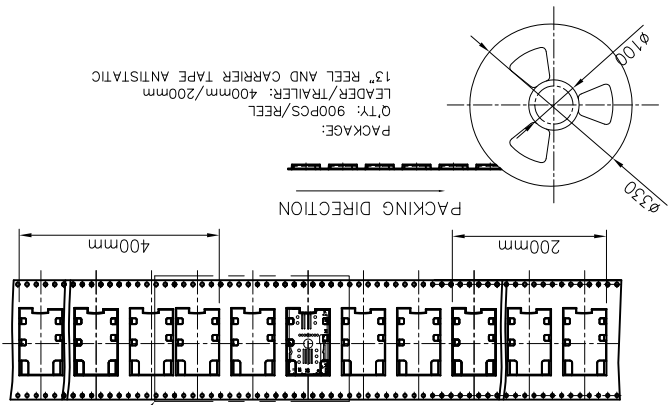
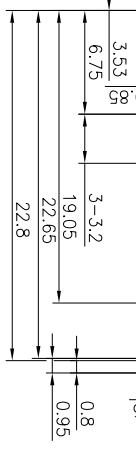
Holder Pin Definition

NANO SIM	NAME
S1,S11,S2,S12	Vcc
S3,S13	RST
S4,S5,S14,S15	CLK
S6,S7,S16,S17	I/O
S8,S18	Vpp
S9,S10,S19,S20	GND

SIM Block Pin Definition

Pin	NAME
C1	DAT2
C2	CD/DAT3
C3	CMD
C4	Vpp
C5	CLK
C6	Vss
C7	DAT0
C8	DAT1

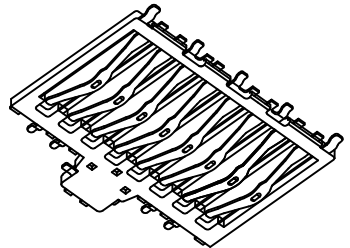
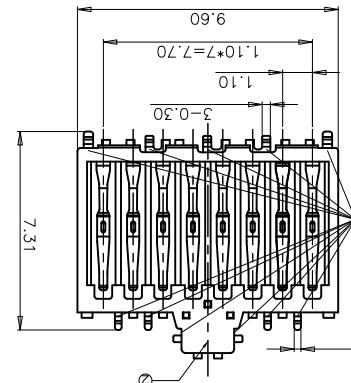
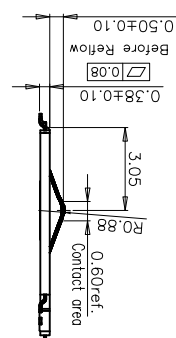
USD Block Pin Definition



PACKAGING DRAWING

DETAILS A  
NOT TO SCALE

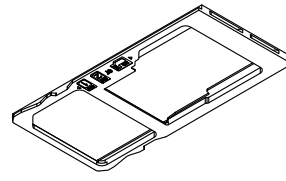
<p>UNLESS OTHERWISE SPECIFIED TOLERANCES</p> <p>DECIMALS: ANGLES: TITLE: 0.3H SIM CARD CONN.</p> <p>DWN ALLEN PART NO. MCS-303-B1</p> <p>CHKD KEVIN SCALE:1:1 UNIT: mm</p> <p>APVD ERIC.W SIZE: A3 SHEET:10F 1 REV: A1</p> <p>CUSTOMER COPY</p>												<p>THIS AREA SHOULD BE FREE OF ANY CONDUCTIVE TRACES</p> <p>SMT SOLDER AREA</p> <p>OPEN WIRE RESTRICTED AREA (POSSIBLY TOUCH OF COMPONENTS ON PCB)</p>												<p>NANO SIM Pin definition</p> <table border="1"> <tr><th>PIN</th><th>NAME</th></tr> <tr><td>S1,S2</td><td>Vcc</td></tr> <tr><td>S3</td><td>RST</td></tr> <tr><td>S4,S5</td><td>CLK</td></tr> <tr><td>S6,S7</td><td>I/O</td></tr> <tr><td>S8</td><td>Vpp</td></tr> <tr><td>S9,S10</td><td>GND</td></tr> </table>												PIN	NAME	S1,S2	Vcc	S3	RST	S4,S5	CLK	S6,S7	I/O	S8	Vpp	S9,S10	GND												
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<p>NO. PART NAME QTY MATERIAL</p> <p>① Contact 1 NKT-322</p> <p>② Housing 1 LCP 6808</p>												<p>DESCRIPTION</p> <p>Under Plating:Ni 1.25um min</p> <p>Solder area:Plating Au 0.25um min</p> <p>Contact area:Plating Au 0.25um min</p> <p>COLOUR:BLACK</p> <p>UL 94V-0</p>												<p>REMARK</p> <p>T=0.08±0.01mm</p>																																					
<p>3. MECHANICAL:</p> <p>3.1 Contact Force:0.2N Min</p> <p>Humidity 80% R.H MAX</p> <p>2.8 Operating condition:Temperature-20C~+85C;</p> <p>2.7 Durability:3000 Cycles Min.</p> <p>2.6 Solder ability:245±5C, 5±0.5s.</p> <p>2.5 Dielectric withstanding voltage: 500V AC 1 MINUTE.</p> <p>2.4 Insulation Resistance:100MΩ MIN 500V DC</p> <p>2.3 Contact Resistance:60mΩ MAX</p> <p>2.2 Rated voltage:10V DC</p> <p>2.1 Rated current:0.5A Max</p>												<p>2. SPECIALTY:</p> <p>1. MATERIAL:SEE TABLE 1.</p>												<p>NOTES:</p> <p>1. MATERIAL:SEE TABLE 1.</p> <p>2. SPECIALTY:</p> <p>3. MECHANICAL:</p> <p>3.1 Contact Force:0.2N Min</p> <p>Humidity 80% R.H MAX</p> <p>2.8 Operating condition:Temperature-20C~+85C;</p> <p>2.7 Durability:3000 Cycles Min.</p> <p>2.6 Solder ability:245±5C, 5±0.5s.</p> <p>2.5 Dielectric withstanding voltage: 500V AC 1 MINUTE.</p> <p>2.4 Insulation Resistance:100MΩ MIN 500V DC</p> <p>2.3 Contact Resistance:60mΩ MAX</p> <p>2.2 Rated voltage:10V DC</p> <p>2.1 Rated current:0.5A Max</p>																																					
<p>東莞市訊普電子科技有限公司</p>												<p>東莞市訊普電子科技有限公司</p>												<p>東莞市訊普電子科技有限公司</p>																																					

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CUSTOMER COPY		<table border="1"> <tr> <td>APVD</td> <td>ERIC.W</td> <td>SIZE: A3</td> <td>SHEET: 10F 1</td> <td>REV: A1</td> </tr> <tr> <td>CHKD</td> <td>KEVIN</td> <td>SCALE: 1:1</td> <td>UNIT: mm</td> <td></td> </tr> <tr> <td>DWN</td> <td>ALLEN</td> <td>PART NO. MCS-303-C1</td> <td></td> <td></td> </tr> </table>		APVD	ERIC.W	SIZE: A3	SHEET: 10F 1	REV: A1	CHKD	KEVIN	SCALE: 1:1	UNIT: mm		DWN	ALLEN	PART NO. MCS-303-C1			<table border="1"> <tr> <td>X.XX</td> <td>: ±0.10</td> </tr> <tr> <td>X.X</td> <td>: ±0.20</td> </tr> <tr> <td>X</td> <td>: ±0.5</td> </tr> <tr> <td>X.X</td> <td>: ±1</td> </tr> </table>	X.XX	: ±0.10	X.X	: ±0.20	X	: ±0.5	X.X	: ±1	<p>DECIMALS: ANGLES: TITLE: 0.3H Micro SD CARD BLOCK CONN.</p>
APVD	ERIC.W	SIZE: A3	SHEET: 10F 1	REV: A1																								
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東莞市訊普電子科技有限公司		UNLESS OTHERWISE SPECIFIED TOLERANCES																										
D	REMARK	DESCRIPTION	NO. PART NAME QTY MATERIAL	<p>1. Touch area of contact tips, no electrical function and only for mechanical function during SMT process.</p> <p>2. Don't brush Tin pasted on the area</p>																								
	UL 94V-0	COLOUR: BLACK	① Contact 1 COPPER ALLOY	<p>3. Pad area (only for mechanical function)</p> <p>4. Open wire restricted area</p> <p>5. Connector outline</p> <p>6. Soldering Pad area</p>																								
	T=0.08±0.01mm	Contact Area: Au 1U"Min; Under plate Ni 50U"Min oil over	② Housing 1 LCP	<table border="1"> <tr><td>PIN</td><td>NAME</td></tr> <tr><td>C1</td><td>DATA2</td></tr> <tr><td>C2</td><td>CD/DATA3</td></tr> <tr><td>C3</td><td>CMD</td></tr> <tr><td>C4</td><td>VCD</td></tr> <tr><td>C5</td><td>CLK</td></tr> <tr><td>C6</td><td>VSS2</td></tr> <tr><td>C7</td><td>DATA0</td></tr> <tr><td>C8</td><td>DATA1</td></tr> </table>	PIN	NAME	C1	DATA2	C2	CD/DATA3	C3	CMD	C4	VCD	C5	CLK	C6	VSS2	C7	DATA0	C8	DATA1						
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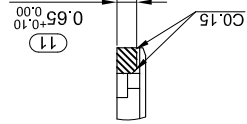
行, 多料, 扭曲变形, 裂痕  
 标注尺寸, 参考3D图档,  
 木图纸, 项目所有的不同卡  
 参考模型。

UNLESS OTHERWISE SPECIFIED TOLERANCES		DECIMALS: ANGLES:		TITLE	
X ±0.5 X ±2°		DWN ALLEN		PART NO. MCS-303-KT1	
X X ±0.20 X X ±1°		CHKD KEVIN		SCALE: 1:1	
X XX ±0.10		APVD ERIC.W		SIZE: A3	
CUSTOMER COPY		SHEET: 1 OF 1		REV: B	

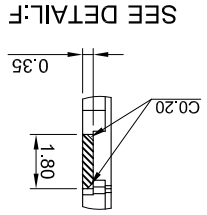
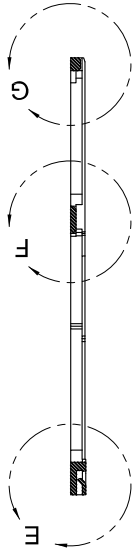
東莞市訊普電子科技有限公司



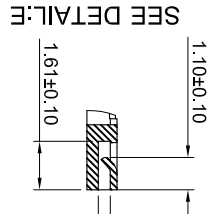
SEE DETAIL:G



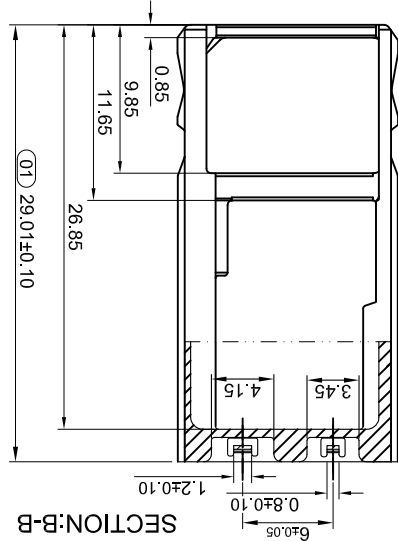
SECTION:A-A



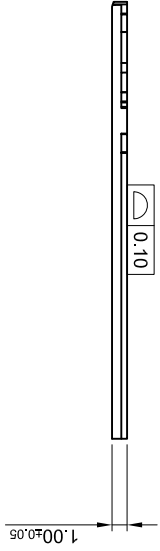
SEE DETAIL:F



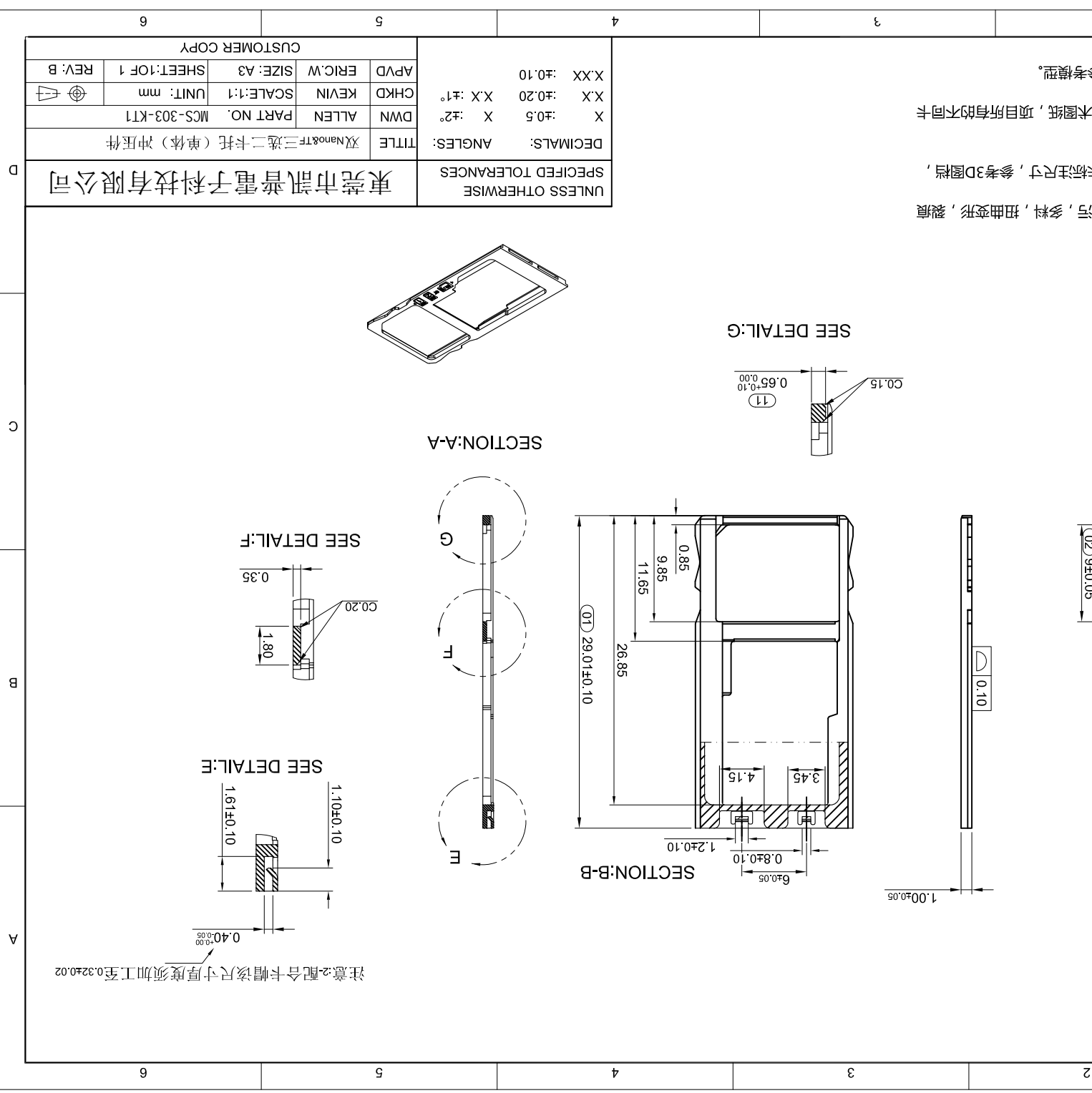
SEE DETAIL:E



SECTION:B-B



注意:2-配合卡帽该尺寸厚度须加工至0.32±0.02



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